

Features

- Great Variety of Product Line-up
 Wavelength: 650nm to 1600nm
 Product form: TO-CAN, Chip-on-Carrier, Module
- High Speed, High Power, High Performance
 Bitrate to 40 Gbps
 High Power to 350mW

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Mitsubishi optical device products support our IT era

Along with widespread Internet use and rapid increase in the amounts of traffic information, optical fiber networks are being extended from trunk lines to subscriber lines.

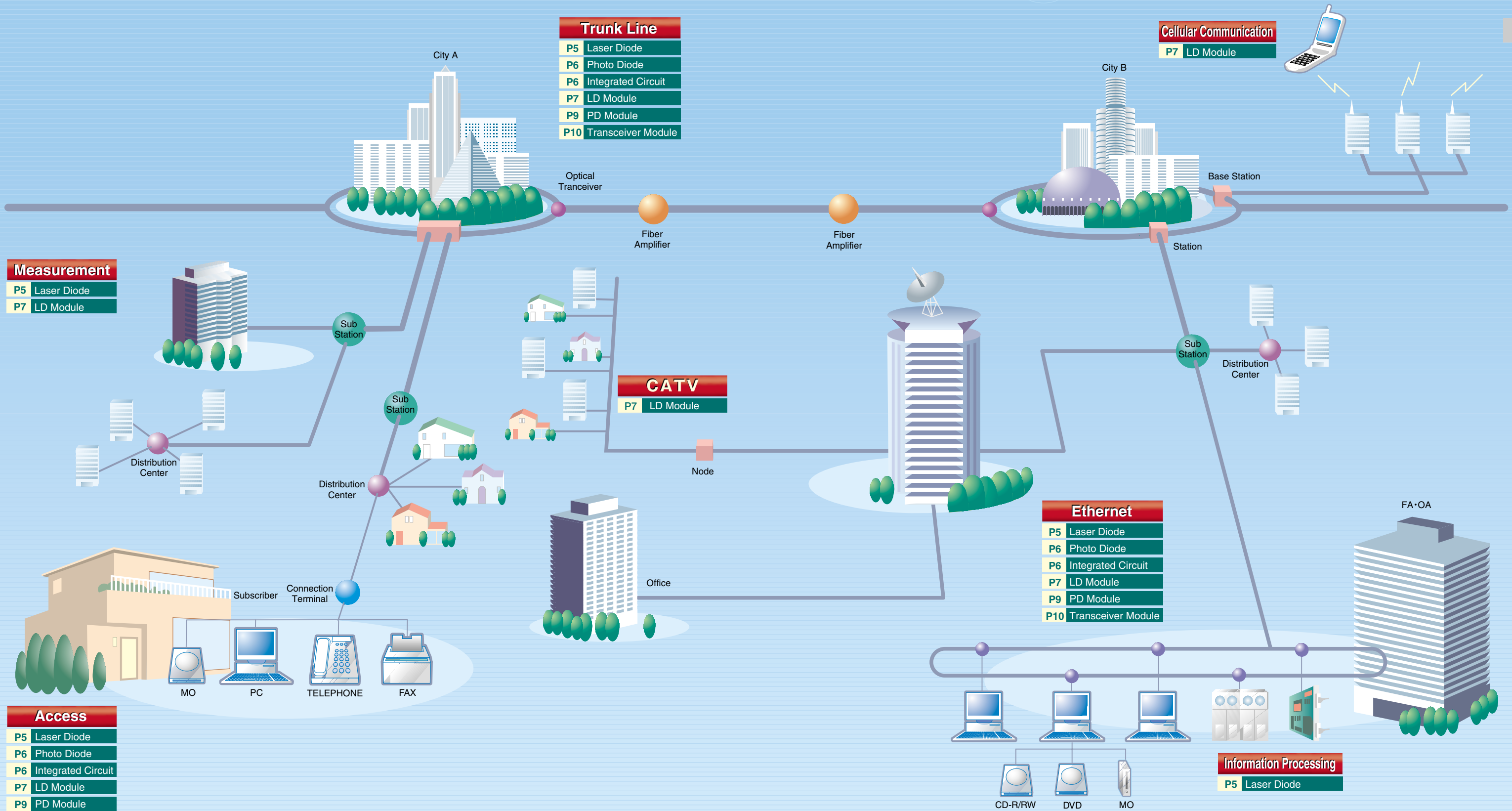
CD was the first optical information-processing device, followed successively by MO, CD-R/RW and DVD±R/RW.

Now, in our IT era, optical technologies are expected to play a major role in a wide variety of areas.

Optical devices from Mitsubishi Electric are fundamental components critical for the IT era.

They allow cutting-edge optical technologies to be integrated into transmission and terminal systems, and serve various fields in both household and industry applications, including optical transmissions, measurements, LAN and information processing.

Mitsubishi optical devices can help you to take the lead in the growing optical industry.

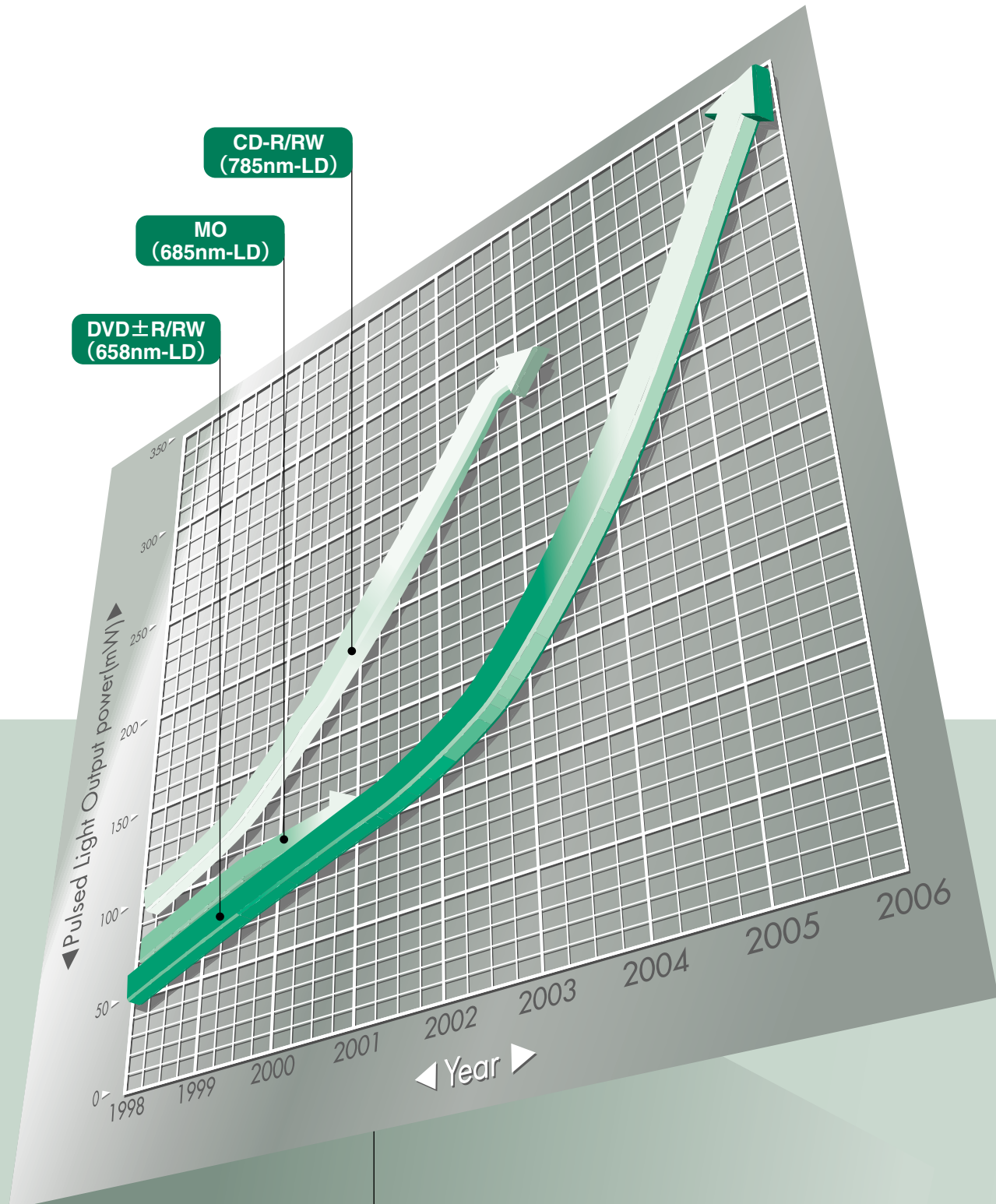


Technology Trend

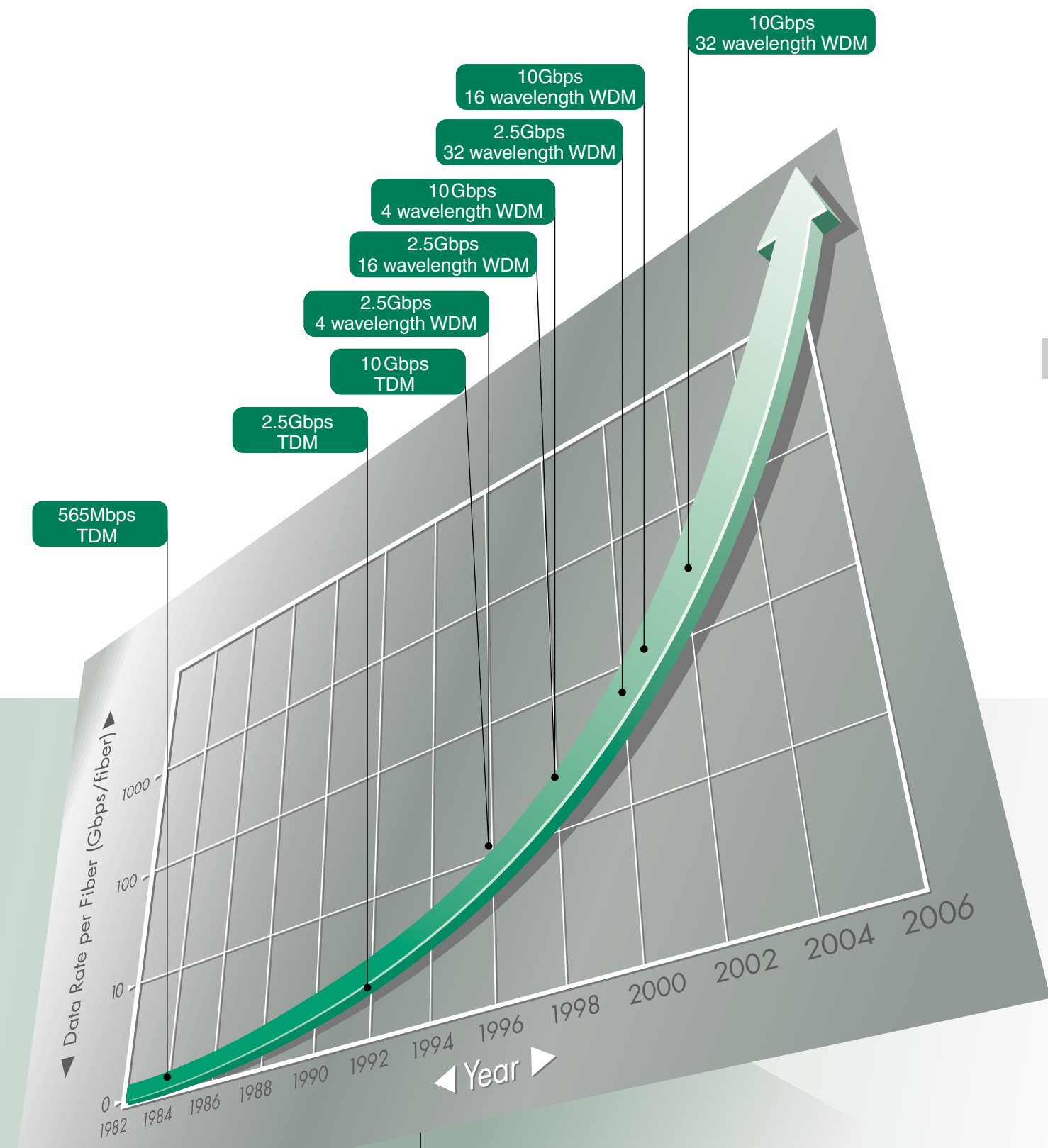
As use of the Internet and mobile phones expands, the fiber-optic communications system that forms the backbone of the information infrastructure is carrying ever increasing loads of data. And the development of smaller and more sophisticated photoelectric devices demanded by the system also continues unabated. Meanwhile, the optical disks that can save these huge quantities of data are evolving from CD-R/RW into recordable DVDs, creating demand for higher output and shorter wavelengths in laser diodes.

Mitsubishi Electric was quickest off the mark in sensing these requirements of the broadband era. We are making a contribution to society by delivering products made with our outstanding developmental powers and quality control.

We will meet the needs of all, with surefire technological prowess and meticulous support.



Power Increase Trend to the Optical Information LDs



TDM : Time Division Multiplexing
WDM : Wavelength Division Multiplexing

Data Rate Increase Trend and Introduction Status to the Optical Communication System Market

Laser Diode for Information Processing & Instrumentation

LDs for DVD \pm R/RW

Type	Wavelength	Power (pulse)	Features
ML1XX21	658nm	160mW	Recordable
ML1XX22	658nm	180mW	Recordable
ML1XX23	658nm	200mW	Recordable
ML1XX24	658nm	230mW	Recordable
ML1XX25	658nm	250mW	Recordable
ML1XX26	658nm	300mW	Recordable
ML1XX27	660nm	350mW	Recordable

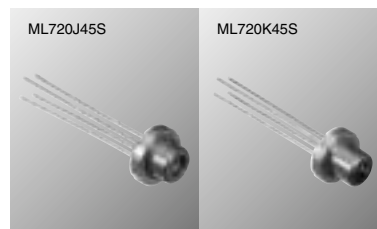


Laser Diode for Optical Communication System

FP-LDs for Subscriber and Data Communication

Type	Wavelength	Power	Features
ML7XX45	1.31 μ m	5mW	~622Mbps for FTTH application
ML7XX46	1.31 μ m	13mW	~622Mbps High optical power LD for PON application
ML7XX19	1.31 μ m	5mW	~2.5Gbps High speed application
ML7XX37*	1.31 μ m	3mW	4Gbps Fiber channel
ML9XX45	1.55 μ m	5mW	~622Mbps for FTTH application

*New Product

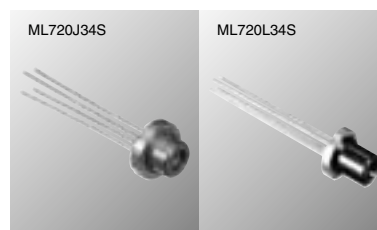


DFB-LDs for Trunk Line, Access Network and Data Communication

Type	Wavelength	Power	Features
ML7XX11	1.31 μ m	5mW	~1.25Gbps
ML7XX16	1.31 μ m	5mW	2.5Gbps, -20~+85°C
ML7XX34*	1.31 μ m	5mW	2.5Gbps, -40~+95°C, 1275~1350nm(25nm spacing)
ML7XX32	1.31 μ m	5mW	4~10Gbps, 0~+85°C
ML9XX16	1.47/1.49 μ m	5mW	~1.25Gbps, with S band for CWDM*(8channel)
ML9XX11	1.51/1.53/1.55 μ m	5mW	~1.25Gbps, with C band for CWDM*(8channel)
ML9XX22	1.57/1.59/1.61 μ m	5mW	~1.25Gbps, with L band for CWDM*(8channel)
ML9XX40	1.47~1.61 μ m	5mW	2.5Gbps, 0~+85°C, for CWDM*(8channel)
ML9XX43*	1.55 μ m	5mW	2.5Gbps, -20~+95°C

*New Product

*Coarse Wavelength Division Multiplexing

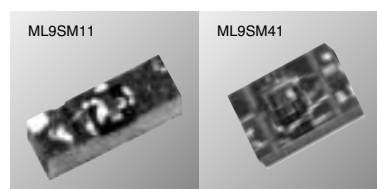


DFB-LDs, EAM-LD for Long Haul WDM* Transmission

Type	Active Diameter	Structure	Features
ML9XX11	1.53~1.56 μ m	10mW	2.5Gbps, ~175km reach, for C-band 47channel
ML9XX41*	1.55 μ m	5mW	10Gbps single channel EAM-LD

*New Product

*Wavelength Division Multiplexing



Laser Diode for Optical Communication System

High power LDs for Optical Time Domain Reflectometer

Type	Active Diameter	Structure	Features
ML7XX10	1.31 μm	300mW	ϕ 5.6mm CAN package
ML9XX10	1.55 μm	200mW	ϕ 5.6mm CAN package

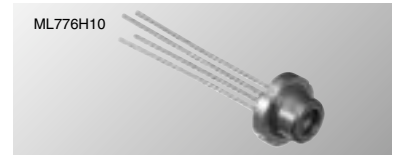


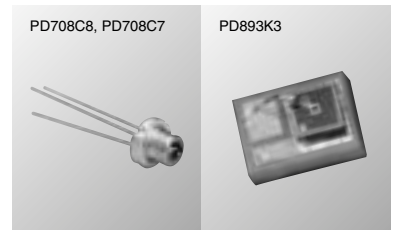
Photo Diode for Optical Communication System

PIN-PDs and APDs for Optical Fiber Communication

Type	Active Diameter	Structure	Features
PD7XX8	ϕ 80 μm	PIN	\sim 1Gbps, TO-56 with ball lens, flat glass
PD7XX7	ϕ 40 μm	PIN	2.5Gbps, diverse package
PD7XX13	ϕ 20 μm	PIN+TiA*	2.5Gbps, PD with TiA, TO-CAN
PD7XX26	ϕ 20 μm	PIN	10Gbps, chip on carrier
PD8XX2	ϕ 50 μm	APD	\sim 1Gbps, TO-56/chip on carrier
PD8XX3	ϕ 35 μm	APD	2.5Gbps, TO-56/chip on carrier
PD8XX4	ϕ 35 μm	APD+TiA*	2.5Gbps, APD with TiA, TO-CAN
PD8XX15*	ϕ 35 μm	APD+TiA*	2.5Gbps lower operating voltage APD with TiA
PD8XX10	ϕ 20 μm	APD	10Gbps, chip on carrier

*New Product

*Trans-Impedance Amplifier

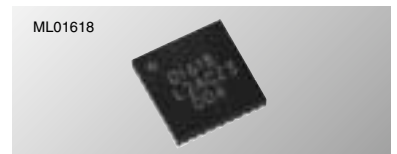


Integrated Circuits for Optical Communication System

EAM/LD Driver ICs

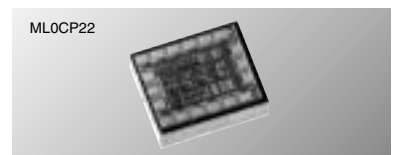
Type	Data Rate	Features
ML01618	10Gbps	With D-FF, SLP package
ML0CP18	10Gbps	With D-FF, Bare chip
ML01720	11.3Gbps	3.3V, with APC*/LPS*, 4mmSLP package
ML01721	11.3Gbps	3.3V/5V, with pulse shape control/LPS*, 4mmSLP package

*APC : Automatic Power Control *LPS : Low Power Start up



Transimpedance Preamplifier ICs

Type	Data Rate	Features
ML0CP22	11.3Gbps	Transimpedance 8k Ω , Chip size 1.05 \times 0.85mm ²



LD Module for Optical Communication System

DFB-LD Module for Trunk Line

- Multiple package and wavelength availability
- High speed response and reliability

Coaxial Type

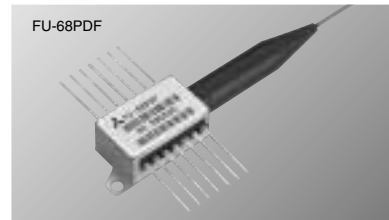
Type	Features
FU-427SDF-F1 series	1310nm
FU-627SDF-F1 series	1550nm
FU-450SDF series*	2.5Gbps 1310nm with Isolator
FU-650SDF series*	2.5Gbps 1470~1610nm CWDM with Isolator

*New Product



Butterfly Type

Type	Features
FU-68SDF-8 series	2.5Gbps 1800ps/nm DWDM C-band 2/10mW
FU-68SDF-9 series	2.5Gbps 3000ps/nm DWDM C-band 2/10mW
FU-68PDF-V5 series	CW Light Source DWDM C-band 10/20mW



LC Receptacle Type

Type	Features
FU-40RDF-S5M2*	2.5Gbps 1310nm for L-16.1 SFP
FU-60RDF-S5M1*	2.5Gbps 1550nm for L-16.2 SFP
FU-60RDF-S6M series*	2.5Gbps for CWDM SFP
FU-400RDF-S5M1*	2.5Gbps 1310nm for S-16.1 SFP
FU-456RDF**	10Gbps 1310nm XMD-MSA package for XFP

*New Product

**Under Development



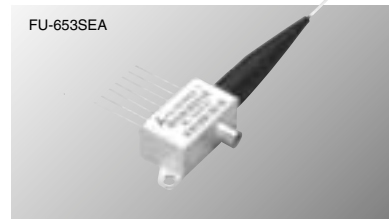
EAM-LD Module for Trunk Line

- High dense long haul transmission. XMD-MSA package is available

Butterfly Type

Type	Features
FU-632SEA-31M series	2.5Gbps 6400ps/nm DWDM C-band
FU-632SEA-61M series	2.5Gbps 12800ps/nm DWDM C-band
FU-653SEA-1M2/4 series	10Gbps 800/400ps/nm GPO connector
FU-653SEA-2M series	10Gbps 800ps/nm DWDM GPO connector
FU-653SEA-1M6 series*	10Gbps 1600ps/nm GPO connector

*New Product



LC Receptacle Type

Type	Features
FU-686REA**	10Gbps 1600ps/nm for XFP-E
FU-610REA**	10Gbps 1600ps/nm XMD-MSA package for XFP

**Under Development



FP-LD Module for Subscriber

Coaxial Type

Type	Features
FU-423SLD-F3M31 series	1310nm 0.2mW
FU-427SLD-F1 series	1310nm 2mW
FU-627SLD-F1 series	1550nm 1.5mW



DFB-LD Module for Mobile Communications

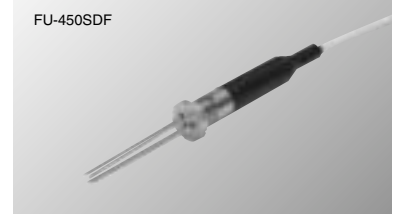
- Multiple package and wavelength availability
- Low distortion and noise.

Coaxial Type(with Isolator)

Type	Features
FU-450SDF series*	4mW 1310nm
FU-650SDF series*	4mW 1470~1610nm CWDM

*New Product

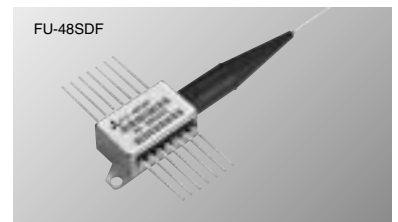
FU-450SDF



Butterfly Type

Type	Features
FU-48SDF-37M9 series	4/8/12mW 1310nm
FU-68SDF-V3M series	10mW 1510~1570nm CWDM

FU-48SDF



DFB-LD Module for CATV

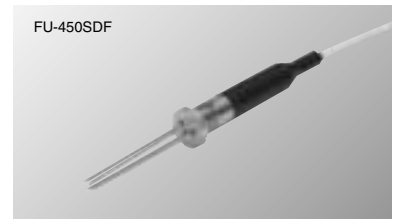
- Multiple package and wavelength availability
- Low distortion and noise.

Coaxial Type(with Isolator)

Type	Features
FU-450SDF series*	4mW 1310nm
FU-650SDF series*	1470~1610nm CWDM

*New Product

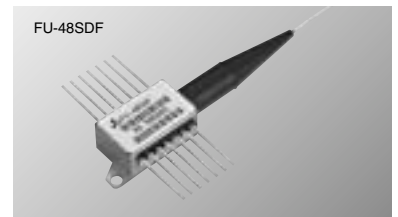
FU-450SDF



Butterfly Type

Type	Features
FU-48SDF-30M series	~10mW 1310nm, NTSC 79ch
FU-48SDF-31M series	~10mW 1310nm, NTSC 112ch

FU-48SDF



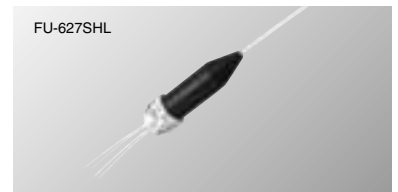
FP-LD Module for OTDR

- High output power under pulse operation.

Coaxial Type

Type	Features
FU-427SLD-F1M54	20mW 1310nm
FU-427SHL series	~120mW 1310nm
FU-427SLD-F1M54	15mW 1550nm
FU-627SHL series	~90mW 1550nm

FU-627SHL



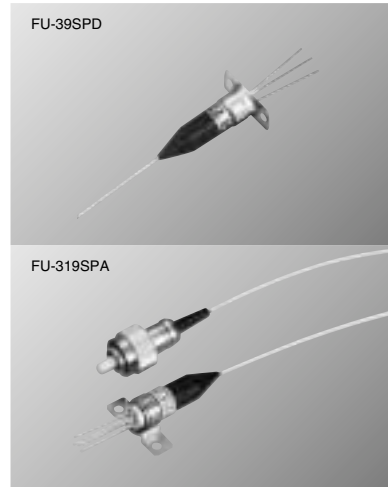
PD Module for Optical Communication System

PD/APD Module for Trunk Line and Access Network

- Multiple package availability
- Low noise, high sensitivity and response

Coaxial Type

Type	Features
FU-39SPD series	PIN-PD
FU-319SPP series	PIN-PD TiA (+3.3V)
FU-318SAP series	APD
FU-319SPA series	APD TiA (+3.3V)

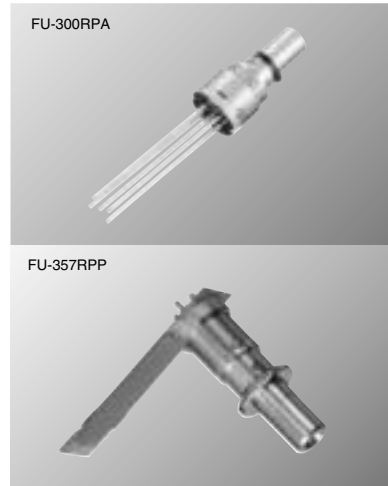


LC Receptacle Type

Type	Features
FU-300RPA*	2.5Gbps APD TiA for SFP
FU-300RPP*	2.5Gbps PIN-PD TiA for SFP
FU-357RPA**	10Gbps APD TiA XMD-MSA package for XFP
FU-357RPP**	10Gbps PIN-PD TiA XMD-MSA package for XFP

*New Product

**Under Development



Optical Transceiver Module

Digital-Optical Transceiver Module(SFP*)

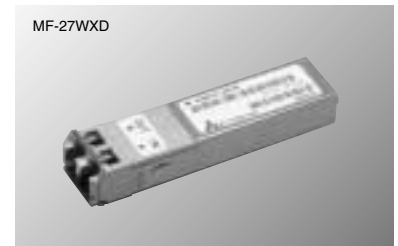
*Small Form Factor Pluggable

- Covering All Application from short to long transmission, distance
- SONET/SDH, CWDM Lineup (note1)
- 2R receive functions (note2)

Type	Data rate	Trans. distance	Optical fiber type
MF-2500FXD-*	2.5Gbps	~15km	LC plug type/Combined type
MF-2500FXE-*	2.5Gbps	~40km	LC plug type/Combined type
MF-2500FXE-*	2.5Gbps	~80km	LC plug type/Combined type
MF-27WXD-*	155Mbps~2.7Gbps	~80km	Multirate CWDM (8wave) /Combined type
MF-27WXE-*	155Mbps~2.7Gbps	~120km	Multirate C-Band CWDM/Combined type

Note1: CWDM:Course Wavelength Division Multiplexing
 Note2: 2R: "Reshaping," "Regenerating" function.

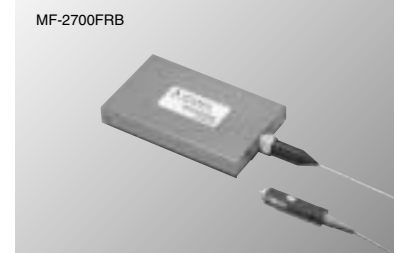
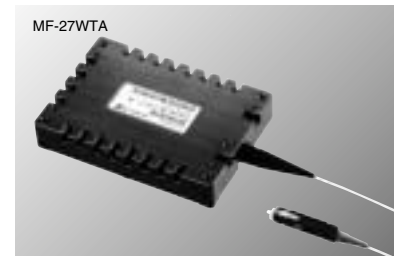
*New Product



WDM Transmitter/Receiver(2R)

- 155M~2.7Gbps Multirate,and small&low power consumption
- WDM C-band100GHz spacing

Type	Data rate	Trans. distance	Optical fiber type
MF-27WTA-M01	155Mbps~2.7Gbps	~90km	Single mode fiber•TX
MF-27WTA-M02	155Mbps~2.7Gbps	~160km	Single mode fiber•TX
MF-2700FRB-	155Mbps~2.7Gbps	~90km	Single mode fiber•RX



Digital-Optical Transceiver Module(XFP)

- Covering All Application from short to long transmission, distance
- SONET/SDH, IEEE802.3ae, DWDM Lineup (note1)

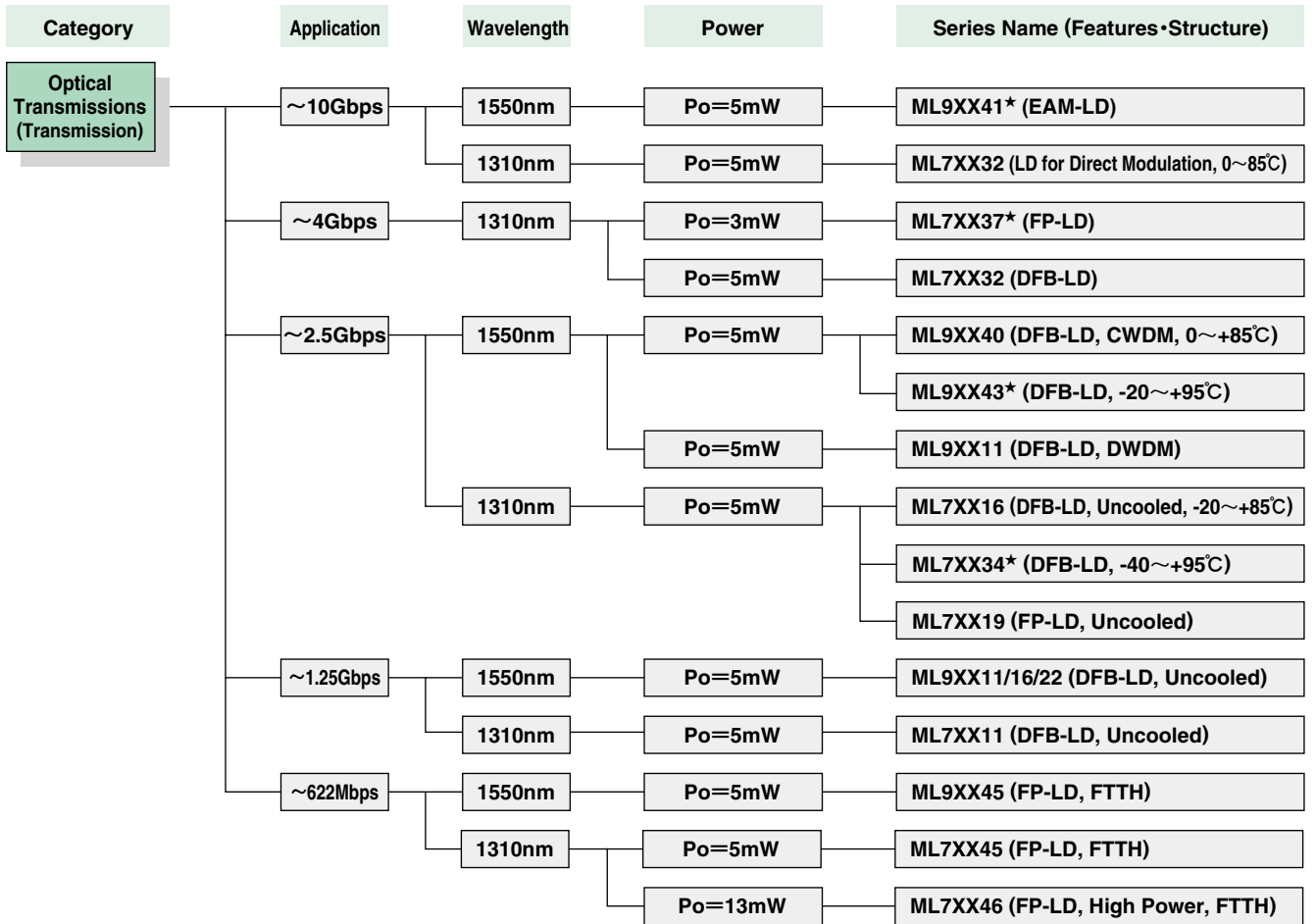
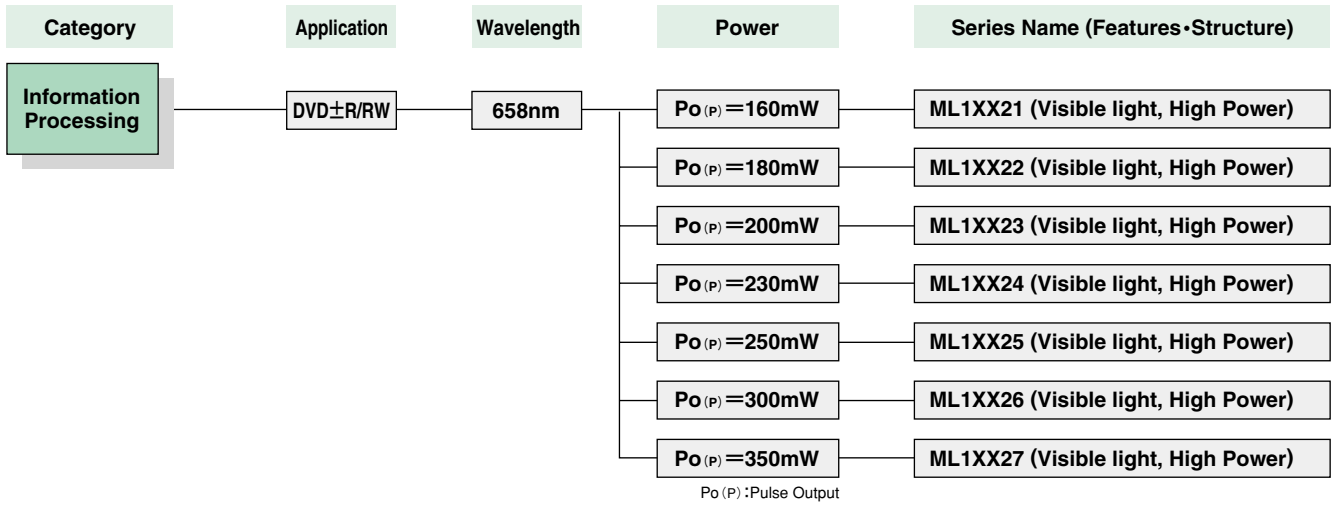
Type	Data rate	Trans. distance	Optical fiber type
XFP			
MF-10KSXA-004ZA**	9.95~10.7Gbps	2km (I-64.1) /10km (LR)	LC Duplex plug type
MF-10KSXA-005ZA**	9.95~10.7Gbps	40km (S-64.2b) /40km (ER)	LC Duplex plug type
MF-10KSXA-006ZA**	9.95~10.7Gbps	80km (P1L1-2D2)	LC Duplex plug type
XFP-Extended			
MF-10KSXB-003ZA*	9.95~10.7Gbps	40km (S-64.2b) /40km (ER)	LC plug type
MF-10KSXB-004ZA*	9.95~10.7Gbps	80km (P1L1-2D2)	LC plug type
MF-10KWXB-002ZA**	9.95~10.7Gbps	80km DWDM	LC Duplex plug type

Note1: DWDM:Dense Wavelength Division MultipleXing

*New Product **Under Development



Selection Guide for Opto-discrete Devices



*New Product

Category	Application	Structure	Active Diameter	Series Name (Features·Structure)
Optical Transmissions (Receive)	10Gbps	InGaAs-PIN	$\phi 20\mu\text{m}$	PD7XX26
		InGaAs-APD	$\phi 20\mu\text{m}$	PD8XX10*
	~2.5Gbps	InGaAs-PIN	$\phi 40\mu\text{m}$	PD7XX7
		InGaAs-APD	$\phi 35\mu\text{m}$	PD8XX3
		PIN-Amp	$\phi 20\mu\text{m}$	PD7XX13 (with Trans Impedance Amp)
		APD-Amp	$\phi 35\mu\text{m}$	PD8XX4 (with Trans Impedance Amp)
	~622Mbps	InGaAs-PIN	$\phi 80\mu\text{m}$	PD7XX8
		InGaAs-APD	$\phi 50\mu\text{m}$	PD8XX2

*New Product

Category	Application	Wavelength	Power	Series Name (Features·Structure)
Optical Transmissions (Measurement)	OTDR	1550nm	Po (P) = 200mW	ML9XX10 (High Power Pulse LD)
		1310nm	Po (P) = 300mW	ML7XX10 (High Power Pulse LD)

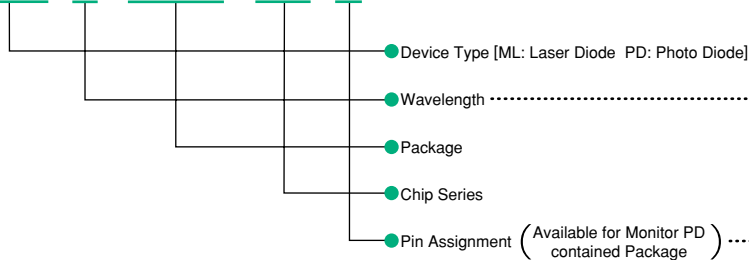
Po (P) : Pulse Output

Category	Application	types	Series Name (Features·Structure)
Optical Transmissions (IC)	10Gbps	Laser driver IC	ML0XX18 (EAM-LD Driver IC with D-FF)
			ML0XX20 (11.3Gbps LD-Driver IC)
			ML0XX21 (11.3Gbps EAM-LD Driver IC)
		Transimpedance IC	ML0CP22

Type Name Definition

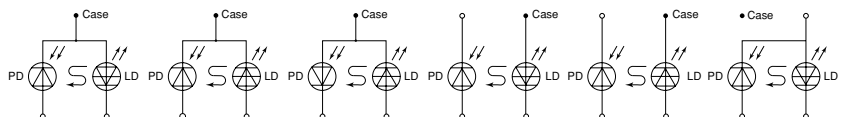
Opto Discreate Devices

ML 7 25B 45 F



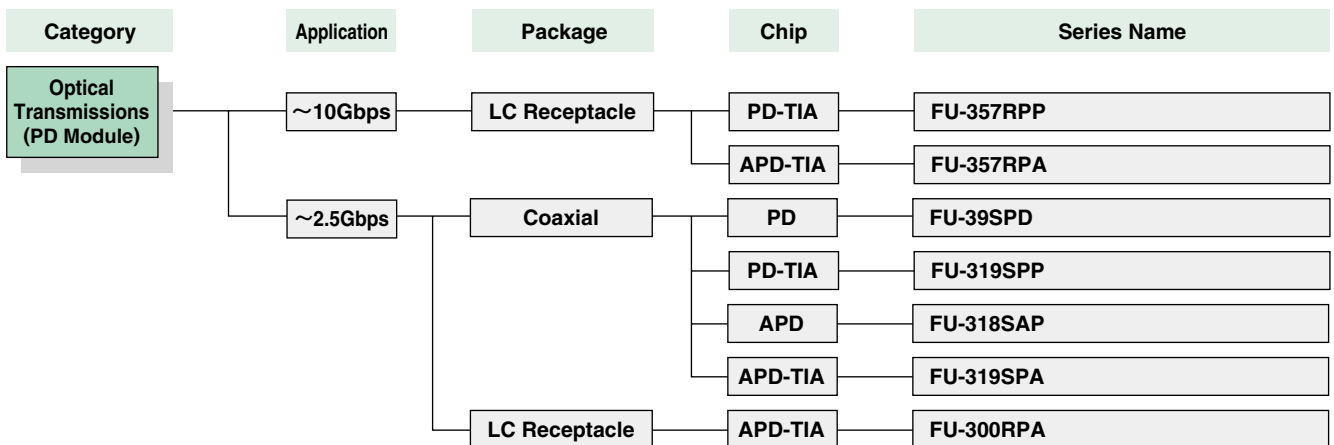
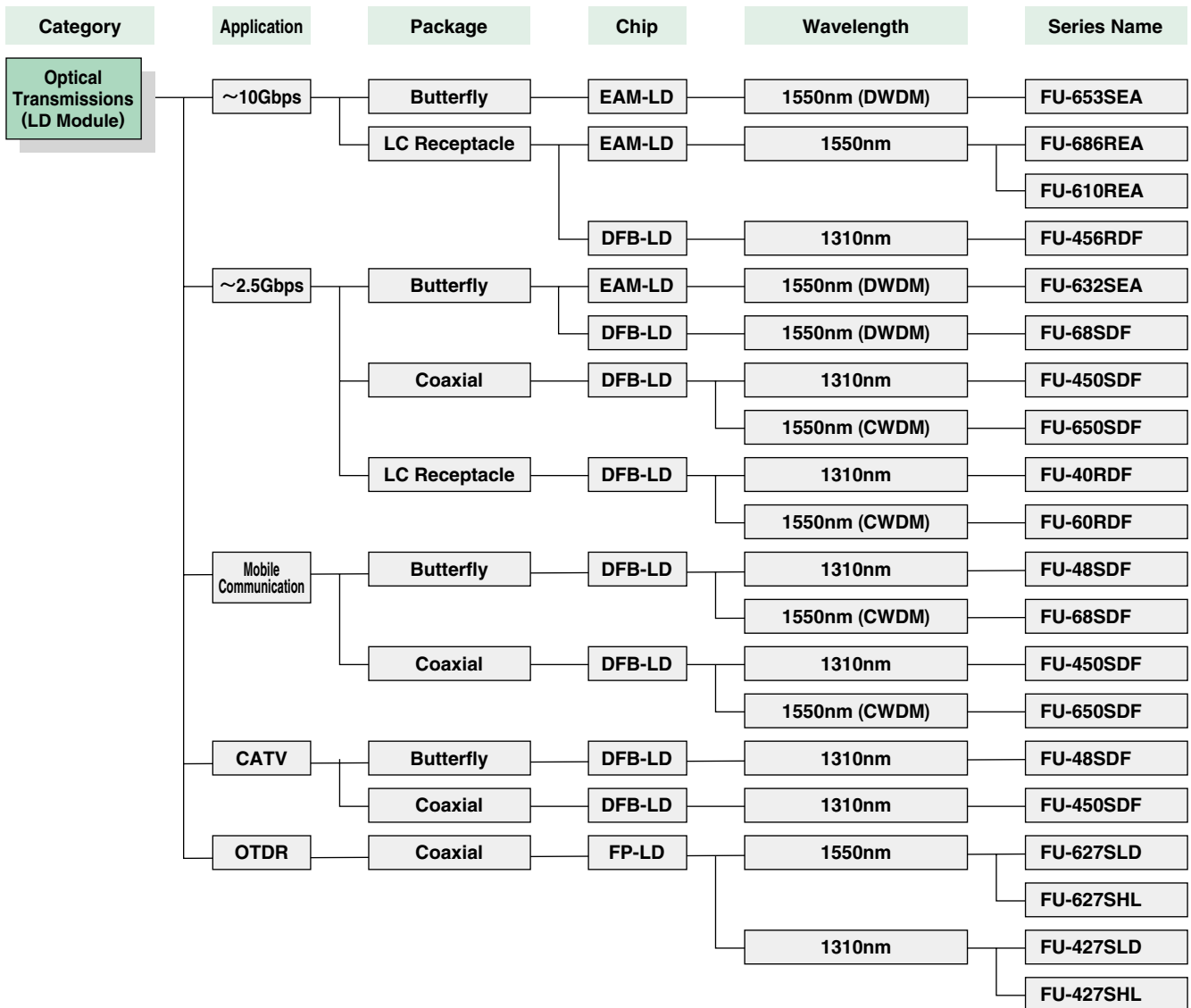
Device Type	Wavelength	Wavelength Range
ML	1	$\lambda \leq 700$
	6	$700 < \lambda \leq 800$
	7	$1250 < \lambda \leq 1400$
	9	$1400 < \lambda$
PD	7	$1000 < \lambda \leq 1600$
	8	

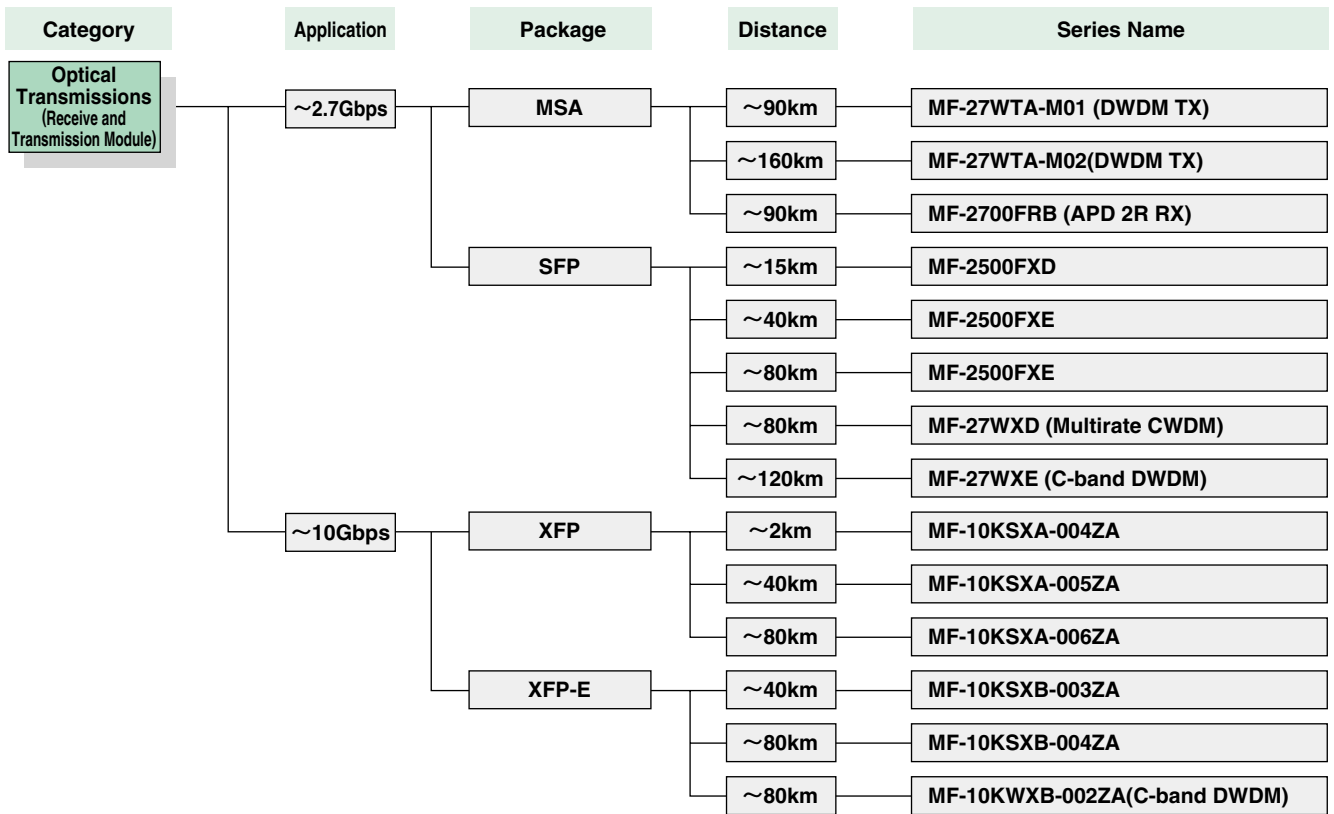
Type	N	C	R	F	E	S
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LD	Anode Common	Cathode Common	Cathode Common	Anode Common	Cathode Common	Floating
PD	Cathode Common	Cathode Common	Anode Common	Floating	Floating	Floating

Selection Guide for Module

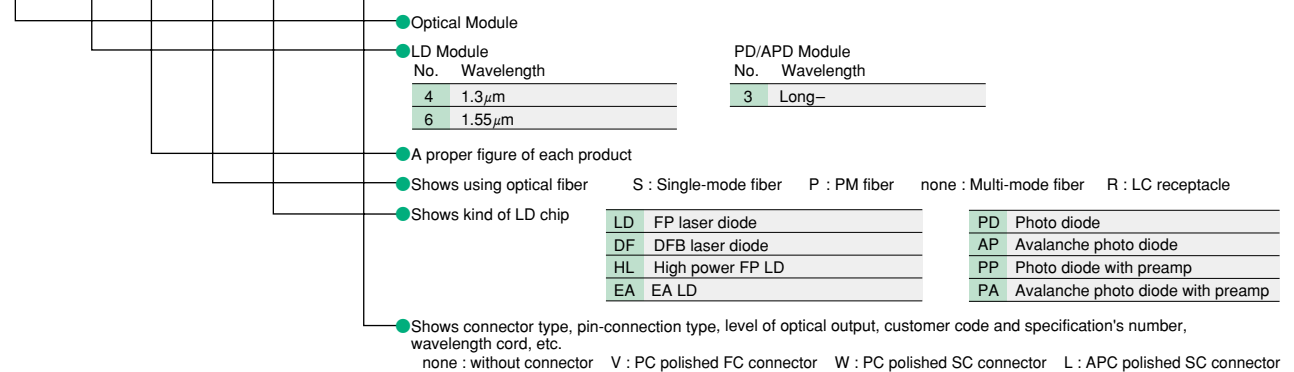




Type Name Definition

DFB-LD/EAM-LD/FP-LD/PD-APD Module

FU-6 36 S DF-FW6M15



Safety Cautions for Use or Disposal of Listed Products

The warnings below apply to all products listed in this pamphlet.

	Warning
Laser Beam	While the laser diode is on, it gives a laser beam. Even if we can't see a laser beam by its wavelength, penetration into the eye by a laser beam or its reflected light may cause eye injury. Prevent the irradiating part or its reflected light from entering the eyes.
Injury	Fiber fragments may cause injury. In cases of fiber bending or breakage, never touch the fragment.
GaAs	Gallium arsenide (GaAs) is used in these products. To avoid danger, strictly observe the following cautions. <ul style="list-style-type: none"> • Never place the products in your mouth. • Never burn or break the products, or use any type of chemical treatment to reduce them to gas or powder. • When disposing of the products, always follow the laws which apply, as well as your own company's internal waste treatment regulations.
Disposal of Flame-Retarded Fiber Core Wire	Flame-retarded resin corresponds to industrial waste and waste plastic as defined in the Wastes Disposal and Public Cleaning Law. In compliance with the Wastes Disposal and Public Cleaning Law, consign disposal to an operator licensed in the treatment and disposal of industrial waste materials. When the local municipality is responsible for the disposal, consign the work to the said municipality. This product is a bromine type flame-retarded resin, containing bromine compounds and antimony trioxide. All disposal operations should be conducted with full consideration of this content.

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